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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	50MHz
Connectivity	SMBus (2-Wire/I ² C), SPI, UART/USART
Peripherals	POR, PWM, Temp Sensor, WDT
Number of I/O	25
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.25K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.25V
Data Converters	A/D 25x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f541-iq

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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4. Package Specifications

4.1. QFP-32 Package Specifications

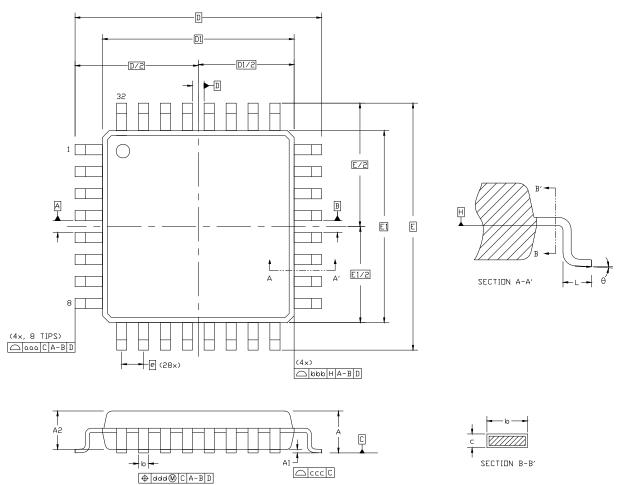


Figure 4.1. QFP-32 Package Drawing

Table 4.1. QFP-32 Package Dimensions

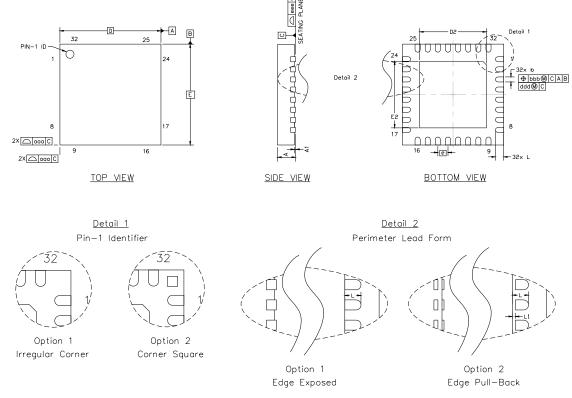
Dimension	Min	Тур	Max	Dimension	Min	Тур	Max
A	— — 1.60			E		9.00 BSC.	
A1	0.05	_	0.15	E1		7.00 BSC.	
A2	1.35	1.40	1.45	L	0.45	0.60	0.75
b	0.30	0.37	0.45	aaa	0.20		
С	0.09 — 0.20			bbb		0.20	
D	9.00 BSC.			CCC		0.10	
D1	7.00 BSC.			ddd		0.20	
е		0.80 BSC.		θ	0°	3.5°	7°

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.

- 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
- 3. This drawing conforms to the JEDEC outline MS-026, variation BBA.
- Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.





4.2. QFN-32 Package Specifications

Figure 4.3. QFN-32 Package Drawing

Dimension	Min	Тур	Max	Dimension	Min	Тур	Max
A	0.80	0.9	1.00	E2	3.20	3.30	3.40
A1	0.00	0.02	0.05	L	0.30	0.40	0.50
b	0.18	0.25	0.30	L1	0.00	_	0.15
D	5.00 BSC.			aaa	_	_	0.15
D2	3.20	3.30	3.40	bbb	_	_	0.15
е	0.50 BSC.			ddd	_	—	0.05
E		5.00 BSC.		eee			0.08

Table 4.3. QFN-32 Package Dimensions

Notes:

- **1.** All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
- **3.** This drawing conforms to the JEDEC Solid State Outline MO-220, variation VHHD except for custom features D2, E2, and L which are toleranced per supplier designation.
- 4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.



C8051F54x

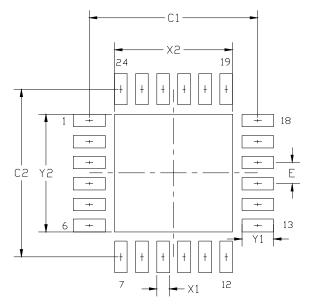


Figure 4.6. QFN-24 Landing Diagram

Dimension	Min	Max	Dimension	Min	Max
C1	3.90	4.00	X2	2.70	2.80
C2	3.90	4.00	Y1	0.65	0.75
E	0.50 BSC		Y2	2.70	2.80
X1	0.20	0.30			

Notes:

General

- 1. All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. This Land Pattern Design is based on the IPC-7351 guidelines.

Solder Mask Design

3. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad.

Stencil Design

- **4.** A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- 5. The stencil thickness should be 0.125 mm (5 mils).
- 6. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
- **7.** A 2x2 array of 1.10 mm x 1.10 mm openings on a 1.30 mm pitch should be used for the center ground pad.

Card Assembly

- 8. A No-Clean, Type-3 solder paste is recommended.
- **9.** The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.



For example, if ADC0GNH = 0xFC, ADC0GNL = 0x00, and GAINADD = 1, GAIN = 0xFC0 = 4032, and the resulting equation is as follows:

$$GAIN = \left(\frac{4032}{4096}\right) + 1 \times \left(\frac{1}{64}\right) = 0.984 + 0.016 = 1.0$$

The table below equates values in the ADC0GNH, ADC0GNL, and ADC0GNA registers to the equivalent gain using this equation.

ADC0GNH Value	ADC0GNL Value	GAINADD Value	GAIN Value	Equivalent Gain
0xFC (default)	0x00 (default)	1 (default)	4032 + 64	1.0 (default)
0x7C	0x00	1	1984 + 64	0.5
0xBC	0x00	1	3008 + 64	0.75
0x3C	0x00	1	960 + 64	0.25
0xFF	0xF0	0	4095 + 0	~1.0
0xFF	0xF0	1	4096 + 64	1.016

For any desired gain value, the GAIN registers can be calculated by the following:

$$\mathsf{GAIN} = \left(\mathsf{gain} - \mathsf{GAINADD} \times \left(\frac{1}{64}\right)\right) \times 4096$$

Equation 5.3. Calculating the ADC0GNH and ADC0GNL Values from the Desired Gain

Where:

GAIN is the 12-bit word of ADC0GNH[7:0] and ADC0GNL[7:4] *GAINADD* is the value of the GAINADD bit (ADC0GNA.0)

gain is the equivalent gain value from 0 to 1.016

When calculating the value of GAIN to load into the ADC0GNH and ADC0GNL registers, the GAINADD bit can be turned on or off to reach a value closer to the desired gain value.

For example, the initial example in this section requires a gain of 0.44 to convert 5 V full scale to 2.2 V full scale. Using Equation 5.3:

$$\mathsf{GAIN} = \left(0.44 - \mathsf{GAINADD} \times \left(\frac{1}{64}\right)\right) \times 4096$$

If GAINADD is set to 1, this makes the equation:

$$GAIN = \left(0.44 - 1 \times \left(\frac{1}{64}\right)\right) \times 4096 = 0.424 \times 4096 = 1738 = 0 \times 06CA$$

The actual gain from setting GAINADD to 1 and ADC0GNH and ADC0GNL to 0x6CA is 0.4399. A similar gain can be achieved if GAINADD is set to 0 with a different value for ADC0GNH and ADC0GNL.



5.3.2. Setting the Gain Value

The three programmable gain registers are accessed indirectly using the ADC0H and ADC0L registers when the GAINEN bit (ADC0CF.0) bit is set. ADC0H acts as the address register, and ADC0L is the data register. The programmable gain registers can only be written to and cannot be read. See Gain Register Definition 5.1, Gain Register Definition 5.2, and Gain Register Definition 5.3 for more information.

The gain is programmed using the following steps:

- 1. Set the GAINEN bit (ADC0CF.0)
- 2. Load the ADC0H with the ADC0GNH, ADC0GNL, or ADC0GNA address.
- 3. Load ADC0L with the desired value for the selected gain register.
- 4. Reset the GAINEN bit (ADC0CF.0)

Notes:

- 1. An ADC conversion should not be performed while the GAINEN bit is set.
- 2. Even with gain enabled, the maximum input voltage must be less than V_{REGIN} and the maximum voltage of the signal after gain must be less than or equal to V_{REF}.

In code, changing the value to 0.44 gain from the previous example looks like:

// in 'C':	
ADC0CF = 0x01;	// GAINEN = 1
ADC0H = 0x04;	// Load the ADC0GNH address
ADC0L = 0x6C;	// Load the upper byte of 0x6CA to ADC0GNH
ADC0H = 0x07;	// Load the ADC0GNL address
ADC0L = 0xA0;	// Load the lower nibble of 0x6CA to ADC0GNL
ADC0H = 0x08;	// Load the ADC0GNA address
ADC0L = 0x01;	// Set the GAINADD bit
ADC0CF &= ~0x01;	// GAINEN = 0
; in assembly	
ORL ADC0CF,#01H	; GAINEN = 1
	, •
MOV ADC0H,#04H	; Load the ADC0GNH address
MOV ADC0H,#04H MOV ADC0L,#06CH	,
	; Load the ADC0GNH address
MOV ADC0L,#06CH	; Load the ADC0GNH address ; Load the upper byte of 0x6CA to ADC0GNH
MOV ADC0L,#06CH MOV ADC0H,#07H	; Load the ADC0GNH address ; Load the upper byte of 0x6CA to ADC0GNH ; Load the ADC0GNL address
MOV ADC0L,#06CH MOV ADC0H,#07H MOV ADC0L,#0A0H	; Load the ADC0GNH address ; Load the upper byte of 0x6CA to ADC0GNH ; Load the ADC0GNL address ; Load the lower nibble of 0x6CA to ADC0GNL
MOV ADC0L,#06CH MOV ADC0H,#07H MOV ADC0L,#0A0H MOV ADC0H,#08H	; Load the ADC0GNH address ; Load the upper byte of 0x6CA to ADC0GNH ; Load the ADC0GNL address ; Load the lower nibble of 0x6CA to ADC0GNL ; Load the ADC0GNA address



SFR Definition 5.7. ADC0CN: ADC0 Control

Bit	7	6	5	4	3	2		1	0	
Nam	e AD0EN	BURSTEN	AD0INT	AD0BUSY	ADOWINT	AD0LJ	ST	AD0C	M[1:0]	
Туре	e R/W	R/W R/W R/W R/W R/W						/W		
Rese	et 0	0 0 0 0 0 0 0						0		
SFR /	Address = 0xE	8; SFR Page = 0x00; Bit-Addressable								
Bit	Name	Function								
7	AD0EN	ADC0 Enab	le Bit.							
		0: ADC0 Dis 1: ADC0 Ena		•			/ersions	6.		
6	BURSTEN	ADC0 Burst	Mode Ena	ble Bit.						
			0: Burst Mode Disabled. 1: Burst Mode Enabled.							
5	AD0INT	ADC0 Conv	ersion Con	nplete Interr	upt Flag.					
		0: ADC0 has not completed a data conversion since AD0INT was last cleared. 1: ADC0 has completed a data conversion.								
4	AD0BUSY	ADC0 Busy	Bit.	Read:			Write:			
		0: ADC0 conversion is not in progress.0: No Effect.1: Initiates ADC0 Conv sion if AD0CM[1:0] = 0 progress.								
3	AD0WINT	ADC0 Wind	ow Compa	re Interrupt	Flag.					
		 This bit must be cleared by software 0: ADC0 Window Comparison Data match has not occurred since this flag was last cleared. 1: ADC0 Window Comparison Data match has occurred. 								
2	AD0LJST	ADC0 Left J	ustify Sele	ct Bit.						
		0: Data in ADC0H:ADC0L registers is right-justified 1: Data in ADC0H:ADC0L registers is left-justified. This option should not be used with a repeat count greater than 1 (when AD0RPT[1:0] is 01b, 10b, or 11b).								
1:0	AD0CM[1:0]									
		 ADC0 Start of Conversion Mode Select. 00: ADC0 start-of-conversion source is write of 1 to AD0BUSY. 01: ADC0 start-of-conversion source is overflow of Timer 1. 10: ADC0 start-of-conversion source is rising edge of external CNVSTR. 11: ADC0 start-of-conversion source is overflow of Timer 2. 								



10. CIP-51 Microcontroller

The MCU system controller core is the CIP-51 microcontroller. The CIP-51 is fully compatible with the MCS-51[™] instruction set; standard 803x/805x assemblers and compilers can be used to develop software. The MCU family has a superset of all the peripherals included with a standard 8051. The CIP-51 also includes on-chip debug hardware (see description in Section 25), and interfaces directly with the analog and digital subsystems providing a complete data acquisition or control-system solution in a single integrated circuit.

The CIP-51 Microcontroller core implements the standard 8051 organization and peripherals as well as additional custom peripherals and functions to extend its capability (see Figure 10.1 for a block diagram). The CIP-51 includes the following features:

- Fully Compatible with MCS-51 Instruction Set
- 50 MIPS Peak Throughput with 50 MHz Clock
- 0 to 50 MHz Clock Frequency
- Extended Interrupt Handler
- Reset Input
- Power Management Modes
- On-chip Debug Logic
- Program and Data Memory Security

10.1. Performance

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute, and usually have a maximum system clock of 12 MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with no instructions taking more than eight system clock cycles.



Table 10.1. CIP-51 Instruction Set Summary

Mnemonic	Description	Bytes	Clock Cycles
Arithmetic Operations			1
ADD A, Rn	Add register to A	1	1
ADD A, direct	Add direct byte to A	2	2
ADD A, @Ri	Add indirect RAM to A	1	2
ADD A, #data	Add immediate to A	2	2
ADDC A, Rn	Add register to A with carry	1	1
ADDC A, direct	Add direct byte to A with carry	2	2
ADDC A, @Ri	Add indirect RAM to A with carry	1	2
ADDC A, #data	Add immediate to A with carry	2	2
SUBB A, Rn	Subtract register from A with borrow	1	1
SUBB A, direct	Subtract direct byte from A with borrow	2	2
SUBB A, @Ri	Subtract indirect RAM from A with borrow	1	2
SUBB A, #data	Subtract immediate from A with borrow	2	2
INC A	Increment A	1	1
INC Rn	Increment register	1	1
INC direct	Increment direct byte	2	2
INC @Ri	Increment indirect RAM	1	2
DEC A	Decrement A	1	1
DEC Rn	Decrement register	1	1
DEC direct	Decrement direct byte	2	2
DEC @Ri	Decrement indirect RAM	1	2
INC DPTR	Increment Data Pointer	1	1
MUL AB	Multiply A and B	1	4
DIV AB	Divide A by B	1	8
DA A	Decimal adjust A	1	1
Logical Operations	,		
ANL A, Rn	AND Register to A	1	1
ANL A, direct	AND direct byte to A	2	2
ANL A, @Ri	AND indirect RAM to A	1	2
ANL A, #data	AND immediate to A	2	2
ANL direct, A	AND A to direct byte	2	2
ANL direct, #data	AND immediate to direct byte	3	3
ORL A, Rn	OR Register to A	1	1
ORL A, direct	OR direct byte to A	2	2
ORL A, @Ri	OR indirect RAM to A	1	2
ORL A, #data	OR immediate to A	2	2
ORL direct, A	OR A to direct byte	2	2
ORL direct, #data	OR immediate to direct byte	3	3
XRL A, Rn	Exclusive-OR Register to A	1	1
XRL A, direct	Exclusive-OR direct byte to A	2	2
XRL A, @Ri	Exclusive-OR indirect RAM to A	1	2



SFR Definition 12.2. SFRPAGE: SFR Page

Bit	7	6	5	4	3	2	1	0	
Name		SFRPAGE[7:0]							
Туре		R/W							
Reset	0	0 0 0 0 0 0 0 0							

SFR Address = 0xA7; SFR Page = All Pages

Bit	Name	Function
7:0	SFRPAGE[7:0]	SFR Page Bits.
		Represents the SFR Page the C8051 core uses when reading or modifying SFRs.
		Write: Sets the SFR Page.
		Read: Byte is the SFR page the C8051 core is using.
		When enabled in the SFR Page Control Register (SFR0CN), the C8051 core will automatically switch to the SFR Page that contains the SFRs of the correspond- ing peripheral/function that caused the interrupt, and return to the previous SFR page upon return from interrupt (unless SFR Stack was altered before a return- ing from the interrupt). SFRPAGE is the top byte of the SFR Page Stack, and push/pop events of this stack are caused by interrupts (and not by reading/writ- ing to the SFRPAGE register)



13.3. External Interrupts INT0 and INT1

The INTO and INT1 external interrupt sources are configurable as active high or low, edge or level sensitive. The INOPL (INTO Polarity) and IN1PL (INT1 Polarity) bits in the IT01CF register select active high or active low; the IT0 and IT1 bits in TCON (Section "23.1. Timer 0 and Timer 1" on page 229) select level or edge sensitive. The table below lists the possible configurations.

IT0	IN0PL	INT0 Interrupt
1	0	Active low, edge sensitive
1	1	Active high, edge sensitive
0	0	Active low, level sensitive
0	1	Active high, level sensitive

IT1	IN1PL	INT1 Interrupt
1	0	Active low, edge sensitive
1	1	Active high, edge sensitive
0	0	Active low, level sensitive
0	1	Active high, level sensitive

INT0 and INT1 are assigned to Port pins as defined in the IT01CF register (see SFR Definition 13.7). Note that INT0 and INT0 Port pin assignments are independent of any Crossbar assignments. INT0 and INT1 will monitor their assigned Port pins without disturbing the peripheral that was assigned the Port pin via the Crossbar. To assign a Port pin only to INT0 and/or INT1, configure the Crossbar to skip the selected pin(s). This is accomplished by setting the associated bit in register XBR0 (see Section "18.3. Priority Crossbar Decoder" on page 150 for complete details on configuring the Crossbar).

IE0 (TCON.1) and IE1 (TCON.3) serve as the interrupt-pending flags for the INT0 and INT1 external interrupts, respectively. If an INT0 or INT1 external interrupt is configured as edge-sensitive, the corresponding interrupt-pending flag is automatically cleared by the hardware when the CPU vectors to the ISR. When configured as level sensitive, the interrupt-pending flag remains logic 1 while the input is active as defined by the corresponding polarity bit (IN0PL or IN1PL); the flag remains logic 0 while the input is inactive. The external interrupt source must hold the input active until the interrupt request is recognized. It must then deactivate the interrupt request before execution of the ISR completes or another interrupt request will be generated.



16.5. Comparator0 Reset

Comparator0 can be configured as a reset source by writing a 1 to the CORSEF flag (RSTSRC.5). Comparator0 should be enabled and allowed to settle prior to writing to CORSEF to prevent any turn-on chatter on the output from generating an unwanted reset. The Comparator0 reset is active-low: if the non-inverting input voltage (on CP0+) is less than the inverting input voltage (on CP0–), the device is put into the reset state. After a Comparator0 reset, the CORSEF flag (RSTSRC.5) will read 1 signifying Comparator0 as the reset source; otherwise, this bit reads 0. The state of the RST pin is unaffected by this reset.

16.6. PCA Watchdog Timer Reset

The programmable Watchdog Timer (WDT) function of the Programmable Counter Array (PCA) can be used to prevent software from running out of control during a system malfunction. The PCA WDT function can be enabled or disabled by software as described in Section "24.4. Watchdog Timer Mode" on page 260; the WDT is enabled and clocked by SYSCLK/12 following any reset. If a system malfunction prevents user software from updating the WDT, a reset is generated and the WDTRSF bit (RSTSRC.5) is set to 1. The state of the RST pin is unaffected by this reset.

16.7. Flash Error Reset

If a Flash read/write/erase or program read targets an illegal address, a system reset is generated. This may occur due to any of the following:

- A Flash write or erase is attempted above user code space. This occurs when PSWE is set to 1 and a MOVX write operation targets an address in or above the reserved space.
- A Flash read is attempted above user code space. This occurs when a MOVC operation targets an address in or above the reserved space.
- A Program read is attempted above user code space. This occurs when user code attempts to branch to an address in or above the reserved space.
- A Flash read, write or erase attempt is restricted due to a Flash security setting (see Section "14.3. Security Options" on page 119).
- A Flash read, write, or erase is attempted when the VDD Monitor is not enabled to the high threshold and set as a reset source.

The FERROR bit (RSTSRC.6) is set following a Flash error reset. The state of the \overline{RST} pin is unaffected by this reset.

16.8. Software Reset

Software may force a reset by writing a 1 to the SWRSF bit (RSTSRC.4). The SWRSF bit will read 1 following a software forced reset. The state of the RST pin is unaffected by this reset.



17.4.1. External Crystal Example

If a crystal or ceramic resonator is used as an external oscillator source for the MCU, the circuit should be configured as shown in Figure 17.1, Option 1. The External Oscillator Frequency Control value (XFCN) should be chosen from the Crystal column of the table in SFR Definition 17.6 (OSCXCN register). For example, an 11.0592 MHz crystal requires an XFCN setting of 111b and a 32.768 kHz Watch Crystal requires an XFCN setting of 001b. After an external 32.768 kHz oscillator is stabilized, the XFCN setting can be switched to 000 to save power. It is recommended to enable the missing clock detector before switching the system clock to any external oscillator source.

When the crystal oscillator is first enabled, the oscillator amplitude detection circuit requires a settling time to achieve proper bias. Introducing a delay of 1 ms between enabling the oscillator and checking the XTLVLD bit will prevent a premature switch to the external oscillator as the system clock. Switching to the external oscillator before the crystal oscillator has stabilized can result in unpredictable behavior. The recommended procedure is:

- 1. Force XTAL1 and XTAL2 to a high state. This involves enabling the Crossbar and writing 1 to the port pins associated with XTAL1 and XTAL2.
- 2. Configure XTAL1 and XTAL2 as analog inputs using.
- 3. Enable the external oscillator.
- 4. Wait at least 1 ms.
- 5. Poll for XTLVLD => 1.
- 6. Enable the Missing Clock Detector.
- 7. Switch the system clock to the external oscillator.

Important Note on External Crystals: Crystal oscillator circuits are quite sensitive to PCB layout. The crystal should be placed as close as possible to the XTAL pins on the device. The traces should be as short as possible and shielded with ground plane from any other traces which could introduce noise or interference.

The capacitors shown in the external crystal configuration provide the load capacitance required by the crystal for correct oscillation. These capacitors are "in series" as seen by the crystal and "in parallel" with the stray capacitance of the XTAL1 and XTAL2 pins.

Note: The desired load capacitance depends upon the crystal and the manufacturer. Refer to the crystal data sheet when completing these calculations.

For example, a tuning-fork crystal of 32.768 kHz with a recommended load capacitance of 12.5 pF should use the configuration shown in Figure 17.1, Option 1. The total value of the capacitors and the stray capacitance of the XTAL pins should equal 25 pF. With a stray capacitance of 3 pF per pin, the 22 pF capacitors yield an equivalent capacitance of 12.5 pF across the crystal, as shown in Figure 17.3.



Equation 17.2. C Mode Oscillator Frequency

 $f = (KF)/(R \times V_{DD})$

For example: Assume $V_{DD} = 2.1 \text{ V}$ and f = 75 kHz:

 $f = KF / (C \times VDD)$

0.075 MHz = KF / (C x 2.1)

Since the frequency of roughly 75 kHz is desired, select the K Factor from the table in SFR Definition 17.6 (OSCXCN) as KF = 7.7:

0.075 MHz = 7.7 / (C x 2.1)

C x 2.1 = 7.7 / 0.075 MHz

C = 102.6 / 2.0 pF = 51.3 pF

Therefore, the XFCN value to use in this example is 010b.



System Clock (MHz)	Prescaler	Divider
25	1	312
24.5	1	306
24	1	300
22.1184	1	276
16	1	200
12.25	0	306
12	0	300
11.0592	0	276
8	0	200

Table 19.3. Autobaud Parameters Examples

19.3. LIN Master Mode Operation

The master node is responsible for the scheduling of messages and sends the header of each frame containing the SYNCH BREAK FIELD, SYNCH FIELD, and IDENTIFIER FIELD. The steps to schedule a message transmission or reception are listed below.

- 1. Load the 6-bit Identifier into the LIN0ID register.
- Load the data length into the LINOSIZE register. Set the value to the number of data bytes or "1111b" if the data length should be decoded from the identifier. Also, set the checksum type, classic or enhanced, in the same LINOSIZE register.
- 3. Set the data direction by setting the TXRX bit (LIN0CTRL.5). Set the bit to 1 to perform a master transmit operation, or set the bit to 0 to perform a master receive operation.
- 4. If performing a master transmit operation, load the data bytes to transmit into the data buffer (LIN0DT1 to LIN0DT8).
- Set the STREQ bit (LIN0CTRL.0) to start the message transfer. The LIN controller will schedule the message frame and request an interrupt if the message transfer is successfully completed or if an error has occurred.

This code segment shows the procedure to schedule a message in a transmission operation:

```
LIN0ADR
         = 0x08;
                                 // Point to LINOCTRL
LINODAT |= 0 \times 20;
                                 // Select to transmit data
LINOADR = 0 \times 0E;
                                 // Point to LIN0ID
LINODAT = 0x11;
                                 // Load the ID, in this example 0x11
LINOADR = 0 \times 0B;
                                 // Point to LINOSIZE
LINODAT = ( LINODAT & 0xF0 ) | 0x08;
                                            // Load the size with 8
LINOADR = 0 \times 00;
                                // Point to Data buffer first byte
for (i=0; i<8; i++)
{
   LINODAT = i + 0x41;
                                // Load the buffer with `A', `B', ...
   LIN0ADR++;
                                // Increment the address to the next buffer
}
LINOADR = 0 \times 08;
                                // Point to LIN0CTRL
LINODAT = 0x01;
                                // Start Request
```

The application should perform the following steps when an interrupt is requested.



LIN Register Definition 19.5. LIN0CTRL: LIN0 Control Register

Bit	7	6	5	4	3	2	1	0
Name	STOP	SLEEP	TXRX	DTACK	RSTINT	RSTERR	WUPREQ	STREQ
Туре	W	R/W	R/W	R/W	W	W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

Indirect Address = 0x08

Bit	Name	Function
7	STOP	Stop Communication Processing Bit. (slave mode only)
		This bit always reads as 0.
		0: No effect.
		1: Block the processing of LIN communications until the next SYNC BREAK signal.
6	SLEEP	Sleep Mode Bit. (slave mode only)
		0: Wake the device after receiving a Wakeup interrupt.
		1: Put the device into sleep mode after receiving a Sleep Mode frame or a bus idle timeout.
5	TXRX	Transmit / Receive Selection Bit.
		0: Current frame is a receive operation.
		1: Current frame is a transmit operation.
4	DTACK	Data Acknowledge Bit. (slave mode only)
		Set to 1 after handling a data request interrupt to acknowledge the transfer. The bit
		will automatically be cleared to 0 by the LIN controller.
3	RSTINT	Reset Interrupt Bit.
		This bit always reads as 0.
		0: No effect.
		1: Reset the LININT bit (LIN0ST.3).
2	RSTERR	Reset Error Bit.
		This bit always reads as 0.
		0: No effect. 1: Reset the error bits in LIN0ST and LIN0ERR.
1	WUPREQ	Wakeup Request Bit.
		Set to 1 to terminate sleep mode by sending a wakeup signal. The bit will automati- cally be cleared to 0 by the LIN controller.
0	STREQ	Start Request Bit. (master mode only)
		1: Start a LIN transmission. This should be set only after loading the identifier, data
		length and data buffer if necessary.
		The bit is reset to 0 upon transmission completion or error detection.



22.3. SPI0 Slave Mode Operation

When SPI0 is enabled and not configured as a master, it will operate as a SPI slave. As a slave, bytes are shifted in through the MOSI pin and out through the MISO pin by a master device controlling the SCK signal. A bit counter in the SPI0 logic counts SCK edges. When 8 bits have been shifted through the shift register, the SPIF flag is set to logic 1, and the byte is copied into the receive buffer. Data is read from the receive buffer by reading SPI0DAT. A slave device cannot initiate transfers. Data to be transferred to the master device is pre-loaded into the shift register by writing to SPI0DAT. Writes to SPI0DAT are double-buffered, and are placed in the transmit buffer first. If the shift register is empty, the contents of the transmit buffer will immediately be transferred into the shift register. When the shift register already contains data, the SPI will load the shift register with the transmit buffer's contents after the last SCK edge of the next (or current) SPI transfer.

When configured as a slave, SPI0 can be configured for 4-wire or 3-wire operation. The default, 4-wire slave mode, is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 1. In 4-wire mode, the NSS signal is routed to a port pin and configured as a digital input. SPI0 is enabled when NSS is logic 0, and disabled when NSS is logic 1. The bit counter is reset on a falling edge of NSS. Note that the NSS signal must be driven low at least 2 system clocks before the first active edge of SCK for each byte transfer. Figure 22.4 shows a connection diagram between two slave devices in 4-wire slave mode and a master device.

3-wire slave mode is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 0. NSS is not used in this mode, and is not mapped to an external port pin through the crossbar. Since there is no way of uniquely addressing the device in 3-wire slave mode, SPI0 must be the only slave device present on the bus. It is important to note that in 3-wire slave mode there is no external means of resetting the bit counter that determines when a full byte has been received. The bit counter can only be reset by disabling and re-enabling SPI0 with the SPIEN bit. Figure 22.3 shows a connection diagram between a slave device in 3-wire slave mode and a master device.

22.4. SPI0 Interrupt Sources

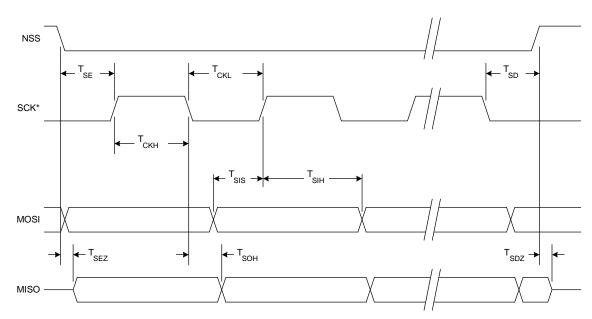
When SPI0 interrupts are enabled, the following four flags will generate an interrupt when they are set to logic 1:

All of the following bits must be cleared by software.

- 1. The SPI Interrupt Flag, SPIF (SPI0CN.7) is set to logic 1 at the end of each byte transfer. This flag can occur in all SPI0 modes.
- 2. The Write Collision Flag, WCOL (SPI0CN.6) is set to logic 1 if a write to SPI0DAT is attempted when the transmit buffer has not been emptied to the SPI shift register. When this occurs, the write to SPI0DAT will be ignored, and the transmit buffer will not be written. This flag can occur in all SPI0 modes.
- 3. The Mode Fault Flag MODF (SPI0CN.5) is set to logic 1 when SPI0 is configured as a master, and for multi-master mode and the NSS pin is pulled low. When a Mode Fault occurs, the MSTEN and SPIEN bits in SPI0CN are set to logic 0 to disable SPI0 and allow another master device to access the bus.
- 4. The Receive Overrun Flag RXOVRN (SPI0CN.4) is set to logic 1 when configured as a slave, and a transfer is completed and the receive buffer still holds an unread byte from a previous transfer. The new byte is not transferred to the receive buffer, allowing the previously received data byte to be read. The data byte which caused the overrun is lost.

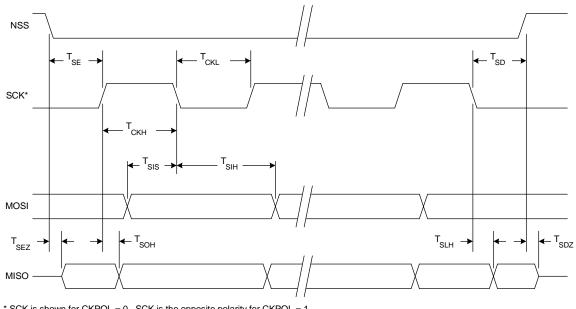


C8051F54x



* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.





* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.





SFR Definition 23.16. TMR3L: Timer 3 Low Byte

Bit	7	6	5	4	3	2	1	0		
Name		TMR3L[7:0]								
Туре		R/W								
Reset	0	0 0 0 0 0 0 0 0								

SFR Address = 0x94; SFR Page = 0x00

Bit	Name	Function
7:0	TMR3L[7:0]	Timer 3 Low Byte.
		In 16-bit mode, the TMR3L register contains the low byte of the 16-bit Timer 3. In 8- bit mode, TMR3L contains the 8-bit low byte timer value.

SFR Definition 23.17. TMR3H Timer 3 High Byte

Bit	7	6	5	4	3	2	1	0	
Name	TMR3H[7:0]								
Туре		R/W							
Reset	0	0 0 0 0 0 0 0							

SFR Address = 0x95; SFR Page = 0x00

Bit	Name	Function
7:0	TMR3H[7:0]	Timer 3 High Byte.
		In 16-bit mode, the TMR3H register contains the high byte of the 16-bit Timer 3. In 8- bit mode, TMR3H contains the 8-bit high byte timer value.



C2 Register Definition 25.2. DEVICEID: C2 Device ID

Bit	7	6	5	4	3	2	1	0	
Name DEVICEID[7:0]									
Туре	e	R/W							
Rese	et 0	0	0	1	0	1	0	0	
C2 Ac	dress = 0xFD;	SFR Addre	ss = 0xFD; S	SFR Page =	0xF				
Bit	Name				Function				
7:0	DEVICEID[7:	DEVICEID[7:0] Device ID.							
		This read-only register returns the 8-bit device ID: 0x22 (C8051F54x).							

C2 Register Definition 25.3. REVID: C2 Revision ID

Bit	7	6	5	4	3	2	1	0
Nam	me REVID[7:0]							
Туре	Type R/W							
Rese	et Varies	Varies	Varies	Varies	Varies	Varies	Varies	Varies
C2 Ad	ldress = 0xFE	; SFR Addres	ss = 0xFE; S	FR Page = 0	ЭхF			
Bit	Name				Function			
7:0	REVID[7:0]	Revision ID.						
		This read-or	nly register re	eturns the 8-	bit revision I	D. For exam	ple: 0x00 = I	Revision A.

